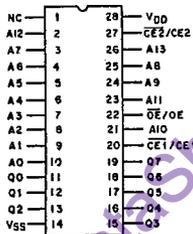


# CDM53128



### TERMINAL ASSIGNMENT

## CMOS 16,384-Word by 8-Bit LSI Static ROM

#### Features:

- Asynchronous operation
  - Fast access time - 250 ns max.
  - Low standby and operating power -  $I_{SBV2} = 2 \mu A$  typical
  - Automatic power-down
  - Mask-programmable chip enables and output enable
  - TTL input and output compatible
  - 28-pin JEDEC standard pin out
- $I_{OPER2} = 10 \text{ mA max. at } t_{CYC} = 1 \mu s;$   
 $= 30 \text{ mA max. at } t_{CYC} = 250 \text{ ns}$

The RCA-CDM53128 is a 131,072-bit asynchronous mask-programmable CMOS READ-ONLY memory organized as 16,384 eight-bit words. The CDM53128 is designed to be used with a wide range of general-purpose microprocessor systems, including the RCA CDP1800 series system. Two chip-enable inputs and an output enable function are provided for memory expansion and output buffer control. Either chip enable (CE1 or CE2) can gate the address and output buffers and power down the chip to the standby

mode. The output enable (OE) controls the output buffers to eliminate bus contention. The polarity of each chip enable and the output enable are user mask-programmable.

The CDM53128 is supplied in 28-lead, hermetic, dual-in-line side-braced ceramic (D suffix), and in 28-lead dual-in-line plastic (E suffix) packages.

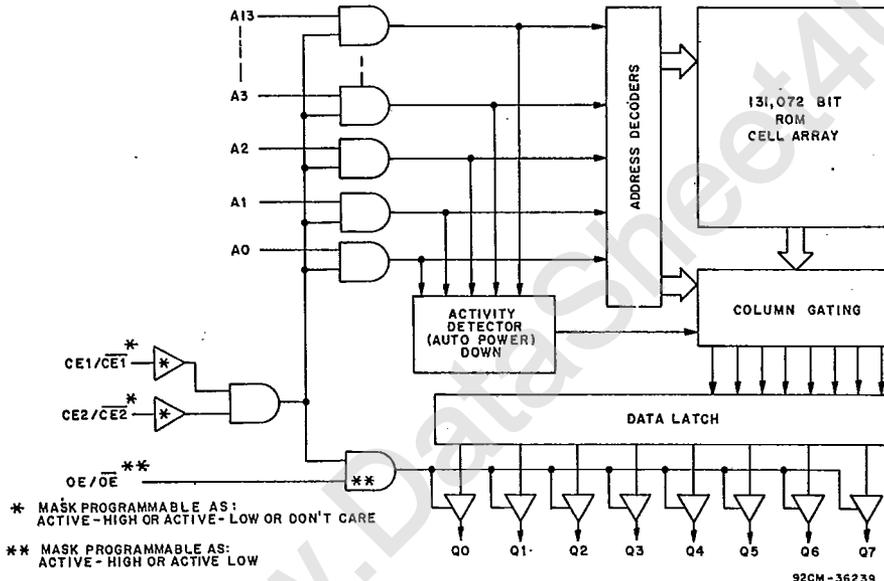


Fig. 1 - Functional block diagram.

- \* MASK PROGRAMMABLE AS: ACTIVE-HIGH OR ACTIVE-LOW OR DON'T CARE
- \*\* MASK PROGRAMMABLE AS: ACTIVE-HIGH OR ACTIVE-LOW

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MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (V<sub>DD</sub>)  
 (Voltage referenced to V<sub>SS</sub> terminal) ..... -0.5 to +7 V  
 INPUT VOLTAGE RANGE, ALL INPUTS ..... -0.5 to V<sub>DD</sub> +0.5 V  
 DC INPUT CURRENT, ANY ONE INPUT ..... ±10 mA  
 POWER DISSIPATION PER PACKAGE (P<sub>D</sub>):  
 For T<sub>A</sub> = -40 to +60°C (PACKAGE TYPE E) ..... 500 mW  
 For T<sub>A</sub> = +60 to +85°C (PACKAGE TYPE E) ..... Derate Linearly at 8 mW/°C to 300 mW  
 For T<sub>A</sub> = -55 to +100°C (PACKAGE TYPE D) ..... 500 mW  
 For T<sub>A</sub> = +100 to +125°C (PACKAGE TYPE D) ..... Derate Linearly at 8 mW/°C to 300 mW  
 DEVICE DISSIPATION PER OUTPUT TRANSISTOR  
 For T<sub>A</sub> = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) ..... 100 mW  
 OPERATING-TEMPERATURE RANGE (T<sub>A</sub>):  
 PACKAGE TYPE D ..... -55 to +125°C  
 PACKAGE TYPE E ..... -40 to +85°C  
 STORAGE-TEMPERATURE RANGE (T<sub>stg</sub>) ..... -65 to +150°C  
 LEAD TEMPERATURE (DURING SOLDERING):  
 At distance 1/16 ± 1/32 in. (1.59 ± 0.79 mm) from case for 10 s maximum ..... +265°C

STATIC ELECTRICAL CHARACTERISTICS at T<sub>A</sub> = -40 to +85°C, V<sub>DD</sub> = 5 V ± 10%, Except as noted

CHARACTERISTIC	CONDITIONS	LIMITS ALL TYPES			UNITS
		Min.	Typ.*	Max.	
Average Operating Device Current <sup>a</sup>	V <sub>IN</sub> = V <sub>IL</sub> , V <sub>IH</sub> ; CE1 and CE2 = V <sub>IH</sub> ; (CE1 and CE2 = V <sub>IL</sub> ) t <sub>cyc</sub> = 1 μs	—	—	15	mA
	t <sub>cyc</sub> = 250 ns	—	—	35	
DC Active Device Current <sup>b</sup>	V <sub>IN</sub> = 0.2 V, V <sub>DD</sub> -0.2 V; CE1 & CE2 = V <sub>DD</sub> -0.2 V; (CE1 & CE2 = 0.2 V) t <sub>cyc</sub> = 1 μs	—	5	10	μA
	t <sub>cyc</sub> = 250 ns	—	15	30	
Standby Device Current <sup>c</sup>	V <sub>IN</sub> = V <sub>IL</sub> , V <sub>IH</sub> ; CE1 and CE2 = V <sub>IH</sub> ; (CE1 and CE2 = V <sub>IL</sub> )	—	—	15	mA
	V <sub>IN</sub> = 0.2 V, V <sub>DD</sub> -0.2 V; CE1 & CE2 = V <sub>DD</sub> -0.2 V; (CE1 & CE2 = 0.2 V)	—	—	50	μA
Output Voltage Low-Level	V <sub>OL</sub>	I <sub>OL</sub> = 3.2 mA	—	—	0.4
	V <sub>OH</sub>	I <sub>OH</sub> = -3.2 mA	2.4	—	—
Input Low Voltage	V <sub>IL</sub>	—	—	—	0.8
Input High Voltage	V <sub>IH</sub>	—	2.2	—	—
Input Leakage Current (Any Input)	I <sub>IN</sub>	V <sub>SS</sub> ≤ V <sub>IN</sub> ≤ V <sub>DD</sub>	—	—	±1
3-State Output Leakage Current	I <sub>OUT</sub>	V <sub>SS</sub> ≤ V <sub>OUT</sub> ≤ V <sub>DD</sub>	—	—	±1
Input Capacitance	C <sub>IN</sub>	f = 1 MHz, T <sub>A</sub> = 25°C	—	5	10
Output Capacitance	C <sub>OUT</sub>	f = 1 MHz, T <sub>A</sub> = 25°C	—	6	12

\*Typical values are for T<sub>A</sub> = 25°C and nominal V<sub>DD</sub>.  
<sup>a</sup>Address inputs toggling, chip enabled, outputs open circuit.  
<sup>b</sup>Inputs stable, chip enabled, outputs open circuit.  
<sup>c</sup>Independent of address input activity, chip disabled.  
<sup>d</sup>TTL inputs.  
<sup>e</sup>CMOS inputs.



Read-Only Memories (ROMs)

**CDM53128**

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RECOMMENDED OPERATING CONDITIONS at  $T_A = -40$  to  $+85^\circ\text{C}$

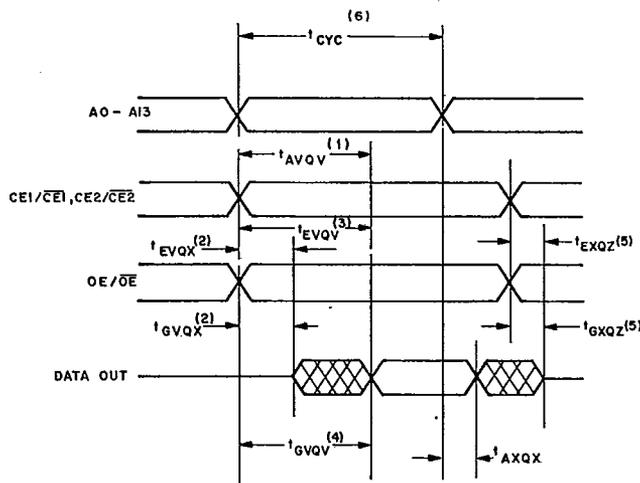
For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	Min.	Max.	
DC Operating Voltage Range	4	6	V
Input Voltage Range	$V_{SS}$	$V_{DD}$	

DYNAMIC ELECTRICAL CHARACTERISTICS at  $T_A = -40$  to  $+85^\circ\text{C}$ ,  $V_{DD} = 5\text{ V} \pm 10\%$ ,

Input  $t_r = 10\text{ ns}$ ;  $C_L = 100\text{ pF}$ , and 1 TTL Load; Input Pulse Levels: 0.8 V to 2.2 V

CHARACTERISTIC		LIMITS		UNITS
		Min.	Max.	
Address Access Time	$t_{AVQV}$	—	250	ns
Chip Enable to Output Active	$t_{EVQX}$	0	—	
Output Enable to Output Active	$t_{GVQX}$	0	—	
Chip Enable Access	$t_{EVQV}$	—	250	
Output Enable to Output Valid	$t_{GVQV}$	—	90	
Data Hold After Address	$t_{AXQX}$	10	—	
Chip Disable to Output High Z	$t_{EXQZ}$	—	90	
Output Disable to Output High Z	$t_{GXQZ}$	—	70	
Cycle Time	$t_{CYC}$	250	—	



- NOTES:
- (1) Assumes  $t_{GVQV}$  &  $t_{EVQV}$  are satisfied.
  - (2) Output Active requires both Chip Enables & Output Enable Active.
  - (3) Assumes  $t_{AVQV}$  &  $t_{GVQV}$  are satisfied.
  - (4) Assumes  $t_{AVQV}$  &  $t_{EVQV}$  are satisfied.
  - (5) Either Invalid Chip Enable or Output Enable causes Output High Z.
  - (6) Generates 10 ns Valid Output Pulses (i.e.,  $t_{CYC} - t_{AVQV} + t_{AXQX}$ )

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Fig. 2 - Timing waveforms.

CDM53128

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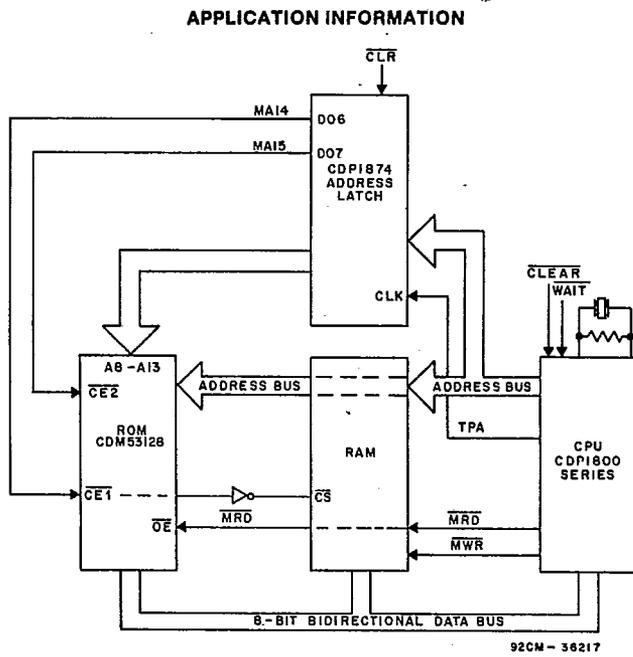


Fig. 3 - Typical CDP1800 series microprocessor system.

**Decoupling Capacitors**

The CDM53128 operates with a low average dc power supply current that varies with cycle time. However, the CDM53128 is a large ROM with many internal nodes. Pre-charging of selected nodes during portions of the memory cycle results in short duration peak currents that can be much higher than the average dc value. The rise and fall

times of the peak current pulses can have a value sufficient to generate unwanted system noise components. To minimize or eliminate the effects of the current spikes, a 0.1- $\mu$ F ceramic decoupling capacitor is recommended between the  $V_{DD}$  and  $V_{SS}$  pins of every ROM device.

